

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE	05MAR21	W. HUANG
B	CHANGES PER ECR-108050	04APR22	B. HEMP
C	CHANGES PER ECR-112397	21MAR23	D. DEVINEN
D	CHANGES PER ECR-116603	18SEP23	D. DEVINEN

HOLE TOLERANCE
UNLESS SPECIFIED
PLATED: +/- 3MILS
NON PLATED: +/- 2MILS

DRILL CHART: TOP to BOTTOM				
FINISHED HOLES IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
□	10.0	PLATED	625	DIA MAX
○	20.0	PLATED	1	DIA MAX
○	36.0	PLATED	14	
◆	40.0	PLATED	4	
◇	45.0	PLATED	17	
△	100.0	PLATED	4	
A	125.0	NON-PLATED	4	

PRIMARY SIDE										
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXXX -.0050			APPROVAL		DATE		<div><div><div></div></div><div>ANALOG DEVICES</div></div> <div>WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887</div>			
			TEMPLATE ENGINEER N/A		N/A					
			HARDWARE SERVICES M. VALE		05MAR21					
			HARDWARE SYSTEMS N/A		N/A					
MATERIAL			TEST ENGINEER N/A		N/A		TITLE FABRICATION ADL5309 CUSTOMER EVAL BOARD Z			
			COMPONENT ENGINEER M. YAN		05MAR21					
			TEST PROCESS N/A		N/A					
			HARDWARE RELEASE K. JABATAN		05MAR21					
FINISH			DESIGNER R. PLANADA		05MAR21		SIZE C	FSCM NO 24355	DRAWING NUMBER 09-067416	REV D
			PTD ENGINEER W. HUANG		05MAR21					
			CHECKER N/A		N/A					
DO NOT SCALE DWG							SCALE 1 / 1		SHEET 1 OF 3	
2 1										

SPECIFICATIONS:

ROHS COMPLIANCE NOTE: HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLIANT THE EU RoHS DIRECTIVE 2002/95/EC

MATERIALS;	ALL LAMINATES AND BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103, MINIMUM Tg>170degC, Td>300degC, U.L. RATING OF 94 V-0
MATERIAL FAMILY;	ISOLA370HR OR S1000-2 OR IT180 OR EQUIVALENT.
CLADDING;	EXTERNAL LAYERS .5 OZ. COPPER, OVERPLATE TO 1 OZ. INTERNAL PLANE LAYERS 1 OZ. COPPER. NOTE: IF THE LAYER STACKUP CONFLICTS WITH THE ABOVE CLADDING SPECIFICATIONS THEN THE LAYER STACKUP SHALL TAKE PRECEDENCE.
SOLDER MASK;	SHALL BE LIQUID PHOTOIMAGEABLE (LPI) APPLIED ON BOTH SIDES OVER BARE COPPER OR GOLD AND SHALL MEET IPC-SM-840 (LATEST REV.) CLASS 3. COLOR GREEN.
SILK SCREEN;	SHALL BE PERMANENT NON-CONDUCTIVE EPOXY INK, COLOR: WHITE SYNTHETIC INKJET PRINTING ALLOWED FOR DENSE BOARDS, COLOR: WHITE
SURFACE FINISH;	ENIG (ELECTROLESS NICKEL/IMMERSION GOLD) PER IPC-4552 LATEST REVISION
INTENTIONAL SHORTS;	IF SUPPLIED DATA INCLUDES A FILE "READ_ME.2", THEN INTENTIONAL NET SHORTS EXIST. CUSTOMER REVIEW AND APPROVAL IS REQUIRED IF SUPPLIED DATA REPORTS ANY CONDITION THAT DOES NOT MATCH "READ_ME.2" FILE PROVIDED.
TEST REQUIREMENTS;	100% NETLIST ELECTRICAL VERIFICATION USING CUSTOMER SUPPLIED IPC-D-356 NETLIST FOR OPENS AND SHORTS WHEN "GERBER DATA" IS PROVIDED. THIS VERIFICATION ALSO REQUIRED FOR "ODB++" DATA PER EMBEDDED NETLIST.

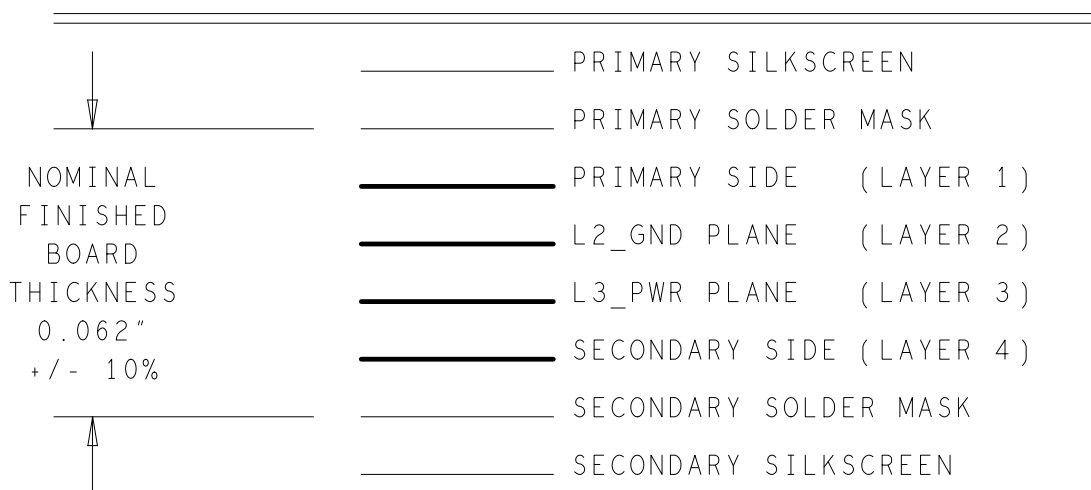
REQUIREMENTS:

- REFER TO IPC-6010 SERIES (LATEST REV.), CLASS 2 FOR FABRICATION UNLESS OTHERWISE SPECIFIED.
- ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00115, (LATEST REVISION.)
- MODIFICATIONS TO THE ARTWORK ARE NOT ALLOWED WITHOUT WRITTEN AUTHORIZATION.
- HOLE PATTERN TOLERANCES FOR UNDIMENSIONED HOLES SHALL BE A DIAMETER OF 0.005 INCHES FROM THEIR TRUE POSITION.
- PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN 0.001 INCH MINIMUM AVERAGE, WITH NO READING LESS THAN .0008 INCH BY CROSS SECTION.
- HOLE DIAMETERS APPLY AFTER PLATING.
- FINISHED CONDUCTOR WIDTHS SHALL NOT BE REDUCED FROM THE NOMINAL INDICATED ON THE MASTER PATTERN, BY MORE THAN THE CONDUCTOR THICKNESS.
- MINIMUM DESIGN LINE WIDTH IS .0045 INCH.
- MINIMUM DESIGN SPACING IS .0048 INCH.
- ~~NON-FUNCTIONAL PAD REMOVAL FROM INNER SIGNAL LAYERS MAY BE PERFORMED AFTER CUSTOMER APPROVAL.~~
- IF PAD SIZES PROVIDED ARE NOT LARGE ENOUGH TO MAINTAIN ANNULAR RING REQUIREMENT, MFGR. MAY REQUEST APPROVAL TO TEAR DROP PADS TO MAINTAIN ANNULAR RING. (AT PAD TO TRACE INTERSECTION ONLY AND ELECTRICAL INTEGRITY MUST BE MAINTAINED.)
- THIEVING MAY BE ADDED TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN ONLY AFTER REVIEW AND APPROVAL FROM THE CUSTOMER:

A. THIEVING TO CARD EDGE, FIDUCIALS, NON-PLATED THROUGH HOLES, ALL OTHER FEATURES TO BE 0.200 INCH MINIMUM.
B. THERE SHALL BE NO THIEVING IN ANY AREAS FREE OF SOLDER MASK OR INTERNAL COPPER PLANES.
- MFGR. TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE IN A CLEAR AREA UNLESS OTHERWISE INDICATED;

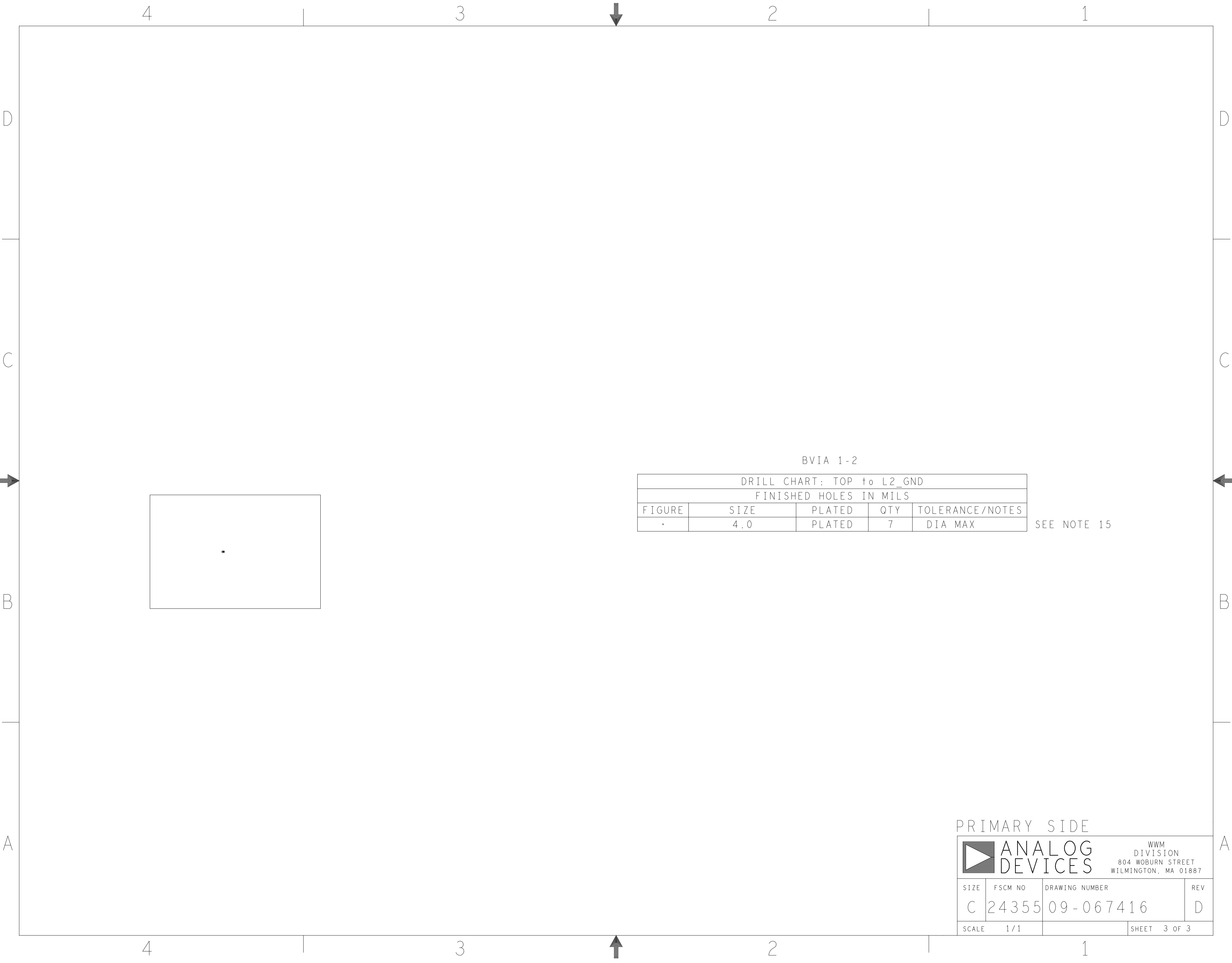
A. U.L. CODE-FLAMMABILITY RATING D. MFGR LOGO
B. DATE CODE (STAMP). E. SUCCESSFUL ELECTRICAL TEST.
C. LOT NUMBER
- REPAIRS PER IPC-7711/21 (LATEST REV.) ARE ALLOWED.
- LASER VIAS TO BE COPPER FILLED/PLATED SHUT AND PLANARIZED.
- BOARDS TO BE SHIPPED IN ARRAY AND KEEP INTACT.
PANEL TO BE SUBJECTED TO CUSTOMER'S APPROVAL.
PANELED SOLDER PASTE STENCIL SHOULD BE SENT TO THE CUSTOMER.

4 LAYER STACKUP



PRIMARY SIDE

	ANALOG DEVICES	WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	09-067416	D
SCALE	1/1	SHEET 2 OF 3	

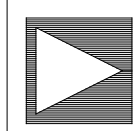


BVIA 1-2

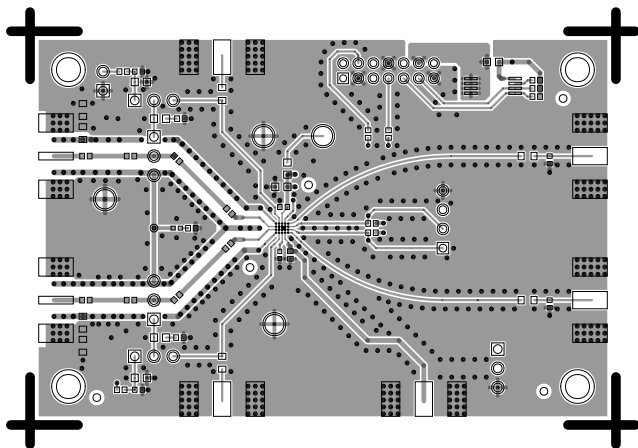
DRILL CHART: TOP to L2_GND				
FINISHED HOLES IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
.	4.0	PLATED	7	DIA MAX

SEE NOTE 15

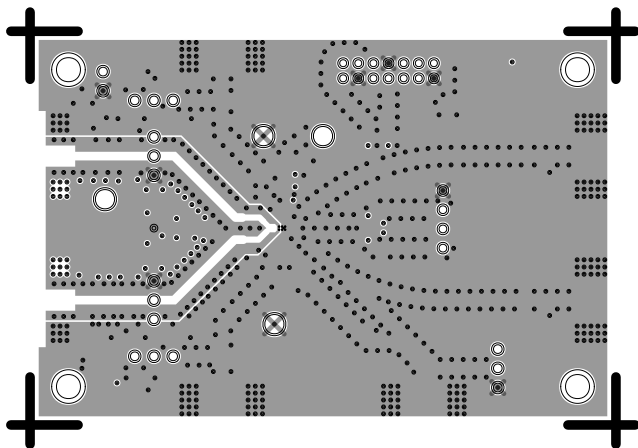
PRIMARY SIDE

		ANALOG DEVICES		WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887	
SIZE	FSCM NO	DRAWING NUMBER		REV	
C	24355	09-067416		D	
SCALE	1 / 1			SHEET 3 OF 3	

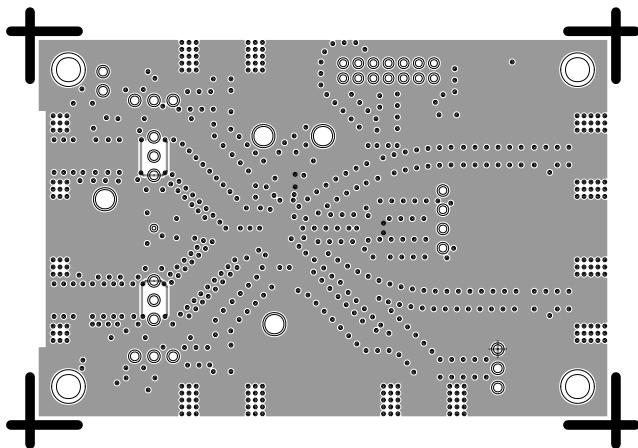
L1 PRIMARY
08-067416-01
REV D



L2 GND
08-067416-07
REV D



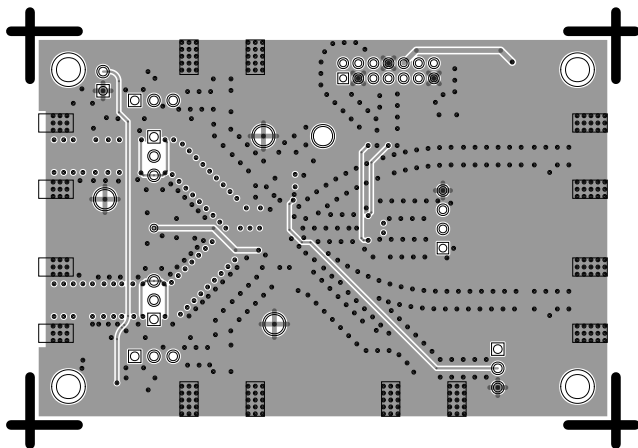
L3 PWR
08-067416-08
REV D



L4 SECONDARY

08-067416-02

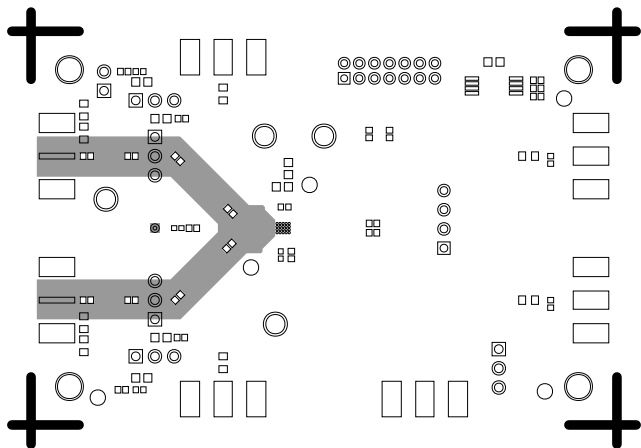
REV D



SOLDERMASK PRIMARY

08-067416-04

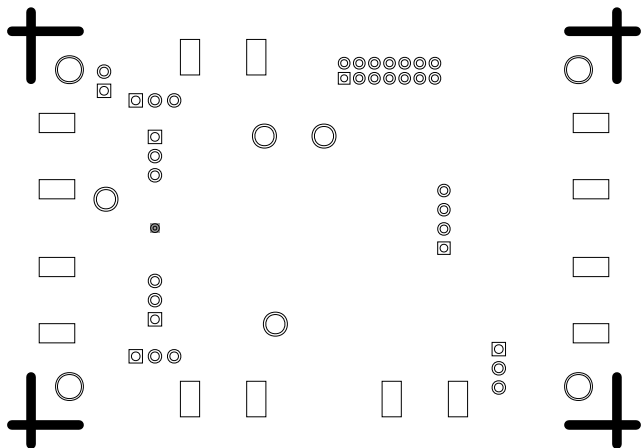
REV D



SOLDERMASK SECONDARY

08-067416-06

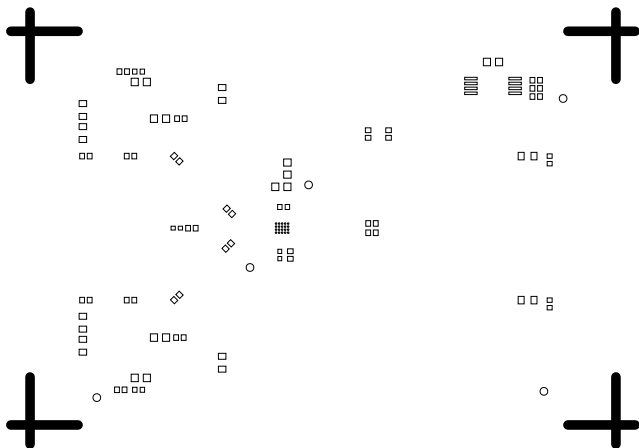
REV D



PASTEMASK PRIMARY

08-067416-09

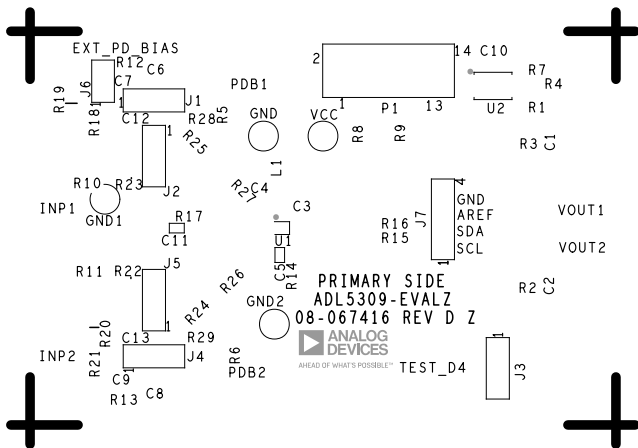
REV D



SILKSCREEN PRIMARY

08-067416-03

REV D



SILKSCREEN SECONDARY
08-067416-05
REV D



GRD
A
C



GRD
A
C

08-067416 REV D Σ
SECONDARY SIDE

